## **Board Stack Report**

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Overlay		0mil	
2	and the about the expension and the part of the second	Top Solder	Solder Resist	0.4mil	3.5
3		L01-TOP		0.6mil	
4		Dielectric 1	FR-4	3.9mil	4.29
5		L02-GND		0.6mil	
6		Dielectric 2	PP-006	6mil	4.1
7		L03-SIG	CF-004	0.6mil	
8		Dielectric 5	PP-006	7.3mil	4.1
9		L04-GND	CF-004	0.6mil	
10		Dielectric 7	PP-006	6mil	4.1
11		L05_PWR	CF-004	0.6mil	
12		Dielectric3	FR-4	7.3mil	4.29
13		L06_PWR	CF-004	0.6mil	
14		Dielectric 8	PP-006	6mil	4.1
15		L07-GND	CF-004	0.6mil	
16		Dielectric 6	PP-006	7.3mil	4.1
17		L08-SIG	CF-004	0.6mil	
18		Dielectric 4	PP-006	6mil	4.1
19		L09-GND		0.6mil	
20		Dielectric 3	FR-4	3.9mil	4.29
21		L10-BOT		0.6mil	
22		Board Layer Stack Bottom Solder	Solder Resist	0.4mil	3.5
23		Board Layer Stack Bottom Overlay		0mil	
	Height : 60.5mil				